

# Product Data Sheet

hm2.0 lower shield, type B22,  
Part No. 244-22600-1



Illustration similar



Perpendicular



Press-fit

- 22 contacts
- termination length 3.4 mm
- for PCB  $\geq 1.44$  mm
- tested according to IEC 61076-4-101



» to product on [www.ept.de](http://www.ept.de)



» to product group hm 2.0

# Product Data Sheet

hm2.0 lower shield, type B22,  
Part No. 244-22600-1



## Technical Specifications

### Basics

Specification	IEC 61076-4-101
Performance Level	2
No. of Contacts	22
Termination Technology	Press-fit
Termination Length	3.4 mm
Operating Temperature Range	-55°C to +125°C

### Material

Contact Material	Bronze
------------------	--------

### Mechanical

Pitch	2.0 mm
Mating Force per Pin	Shielding: max. 1 N
Separating Force per Pin	Shielding: min. 0.15 N
Durability	> 250 mating cycles

### Electrical

Operational Current	1.5 A @ +20°C, 1.0 A @ +70°C
Contact Resistance	max. 20 mΩ
Insulation Resistance	min. 10 <sup>4</sup> MΩ
Test Voltage	750 V r.m.s
Data Transfer Rate	3.125 Gbit/s

### Approval / Compliance

Environment	RoHS compliant
-------------	----------------

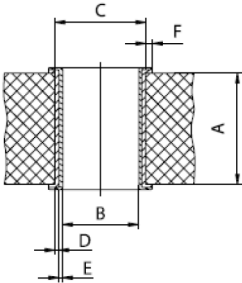
# Product Data Sheet

hm2.0 lower shield, type B22,  
Part No. 244-22600-1



## Hole Specifications

Plated through-hole according to IEC 60352-5



Material	imm. Sn printed circuit boards
<b>Nominal Hole</b>	<b>Ø 0.6 mm</b>
<b>A PCB Thickness</b>	min 1.44 mm
<b>B Plated Hole</b>	Ø 0.60 ±0.05 mm
<b>C Drill Hole</b>	0.70 ±0.02 mm
<b>D Cu Plating</b>	min. 25 µm
<b>E Surface</b>	max. 1.5 µm; imm. Sn plating
<b>F Annular Ring</b>	min. 0.1 mm

Material	Ni, Au printed circuit boards
<b>Nominal Hole</b>	<b>Ø 0.6 mm</b>
<b>A PCB Thickness</b>	min 1.44 mm
<b>B Plated Hole</b>	Ø 0.60 ±0.05 mm
<b>C Drill Hole</b>	0.70 ±0.02 mm
<b>D Cu Plating</b>	min. 25 µm
<b>E Surface</b>	Ni, Au plating, 0.05 - 0.2 µm Au over 2.5 - 5 µm Ni
<b>F Annular Ring</b>	min. 0.1 mm

Material	pure Cu printed circuit boards
<b>Nominal Hole</b>	<b>Ø 0.6 mm</b>
<b>A PCB Thickness</b>	min 1.44 mm
<b>B Plated Hole</b>	Ø 0.60 ±0.05 mm
<b>C Drill Hole</b>	0.70 ±0.02 mm
<b>D Cu Plating</b>	min. 25 µm
<b>E Surface</b>	OSP*, z.B. GLICOAT-SMD (F2) with 0.12 - 0.15 µm
<b>F Annular Ring</b>	min. 0.1 mm

Material	HAL Sn printed circuit boards
<b>Nominal Hole</b>	<b>Ø 0.6 mm</b>
<b>A PCB Thickness</b>	min 1.44 mm
<b>B Plated Hole</b>	Ø 0.60 ±0.05 mm
<b>C Drill Hole</b>	0.70 ±0.02 mm
<b>D Cu Plating</b>	min. 25 µm
<b>E Surface</b>	HAL Sn, 5 - 15 µm
<b>F Annular Ring</b>	min. 0.1 mm

# Product Data Sheet

hm2.0 lower shield, type B22,  
Part No. 244-22600-1

---



## Drawings

Component data for this product you can request through [sales@ept.de](mailto:sales@ept.de)